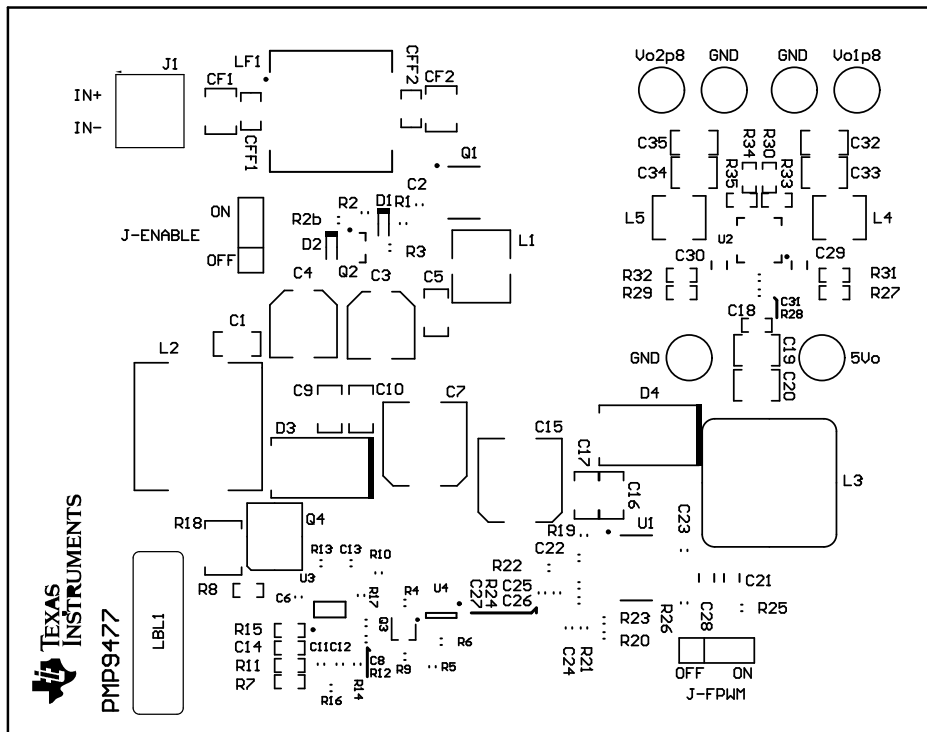
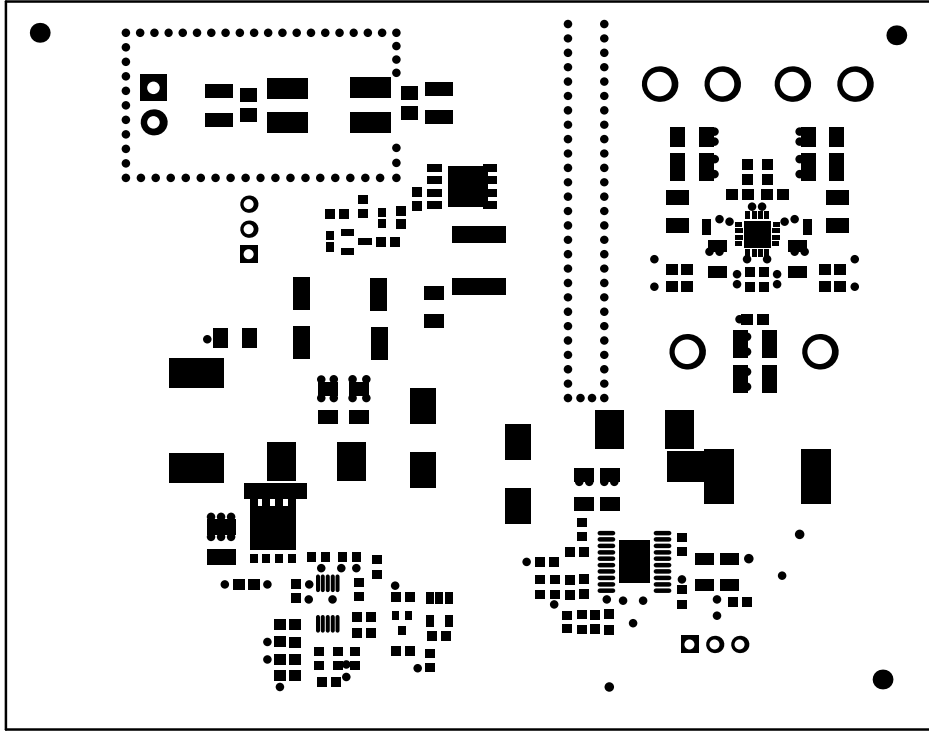
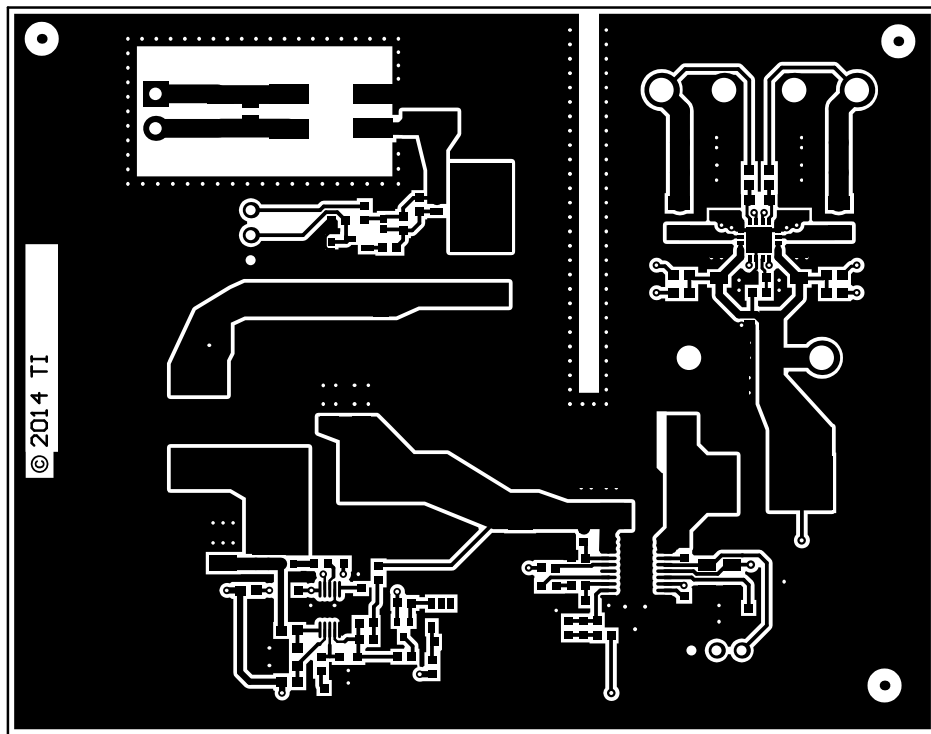




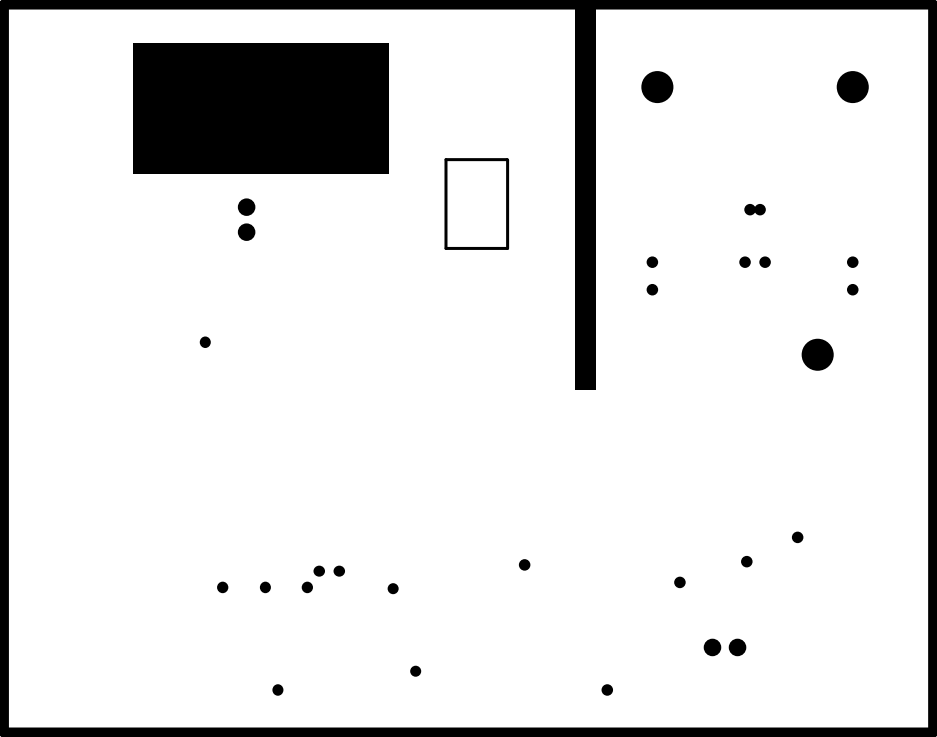
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9477	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 9/3/2014 4:16:01 PM	TEXAS INSTRUMENTS	



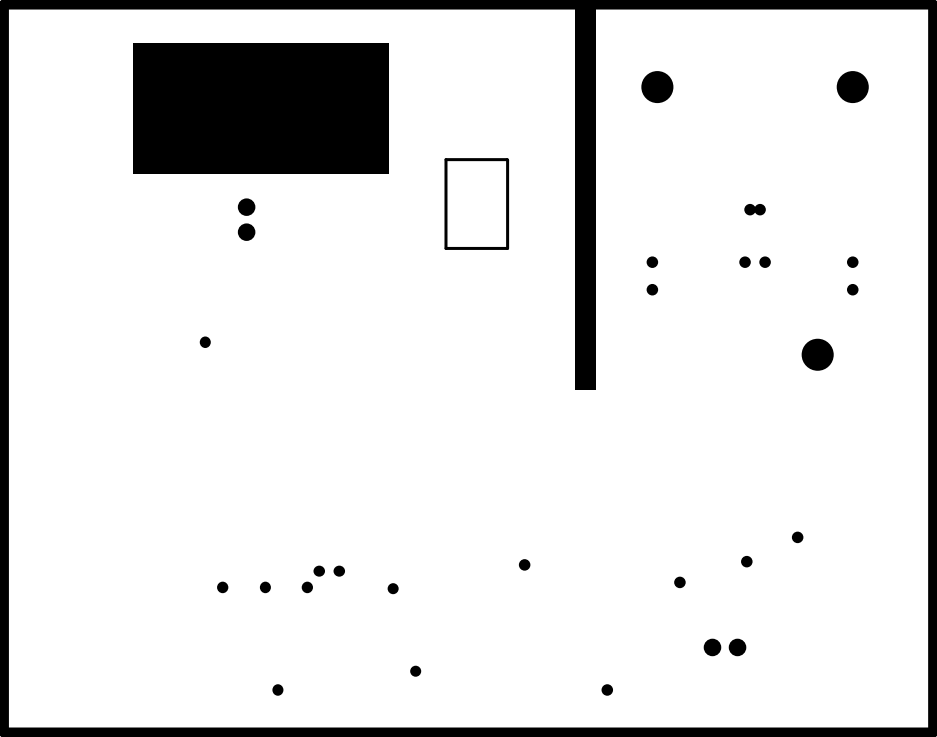
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9477	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 9/3/2014 4:16:02 PM	TEXAS INSTRUMENTS	



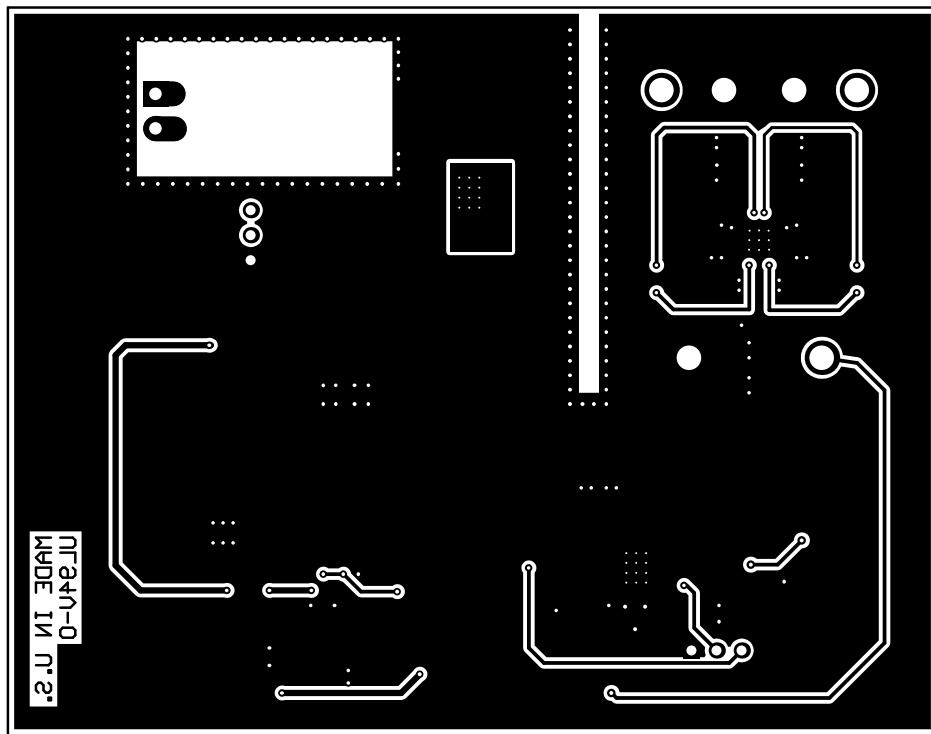
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9477	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 9/3/2014 4:16:02 PM	TEXAS INSTRUMENTS	



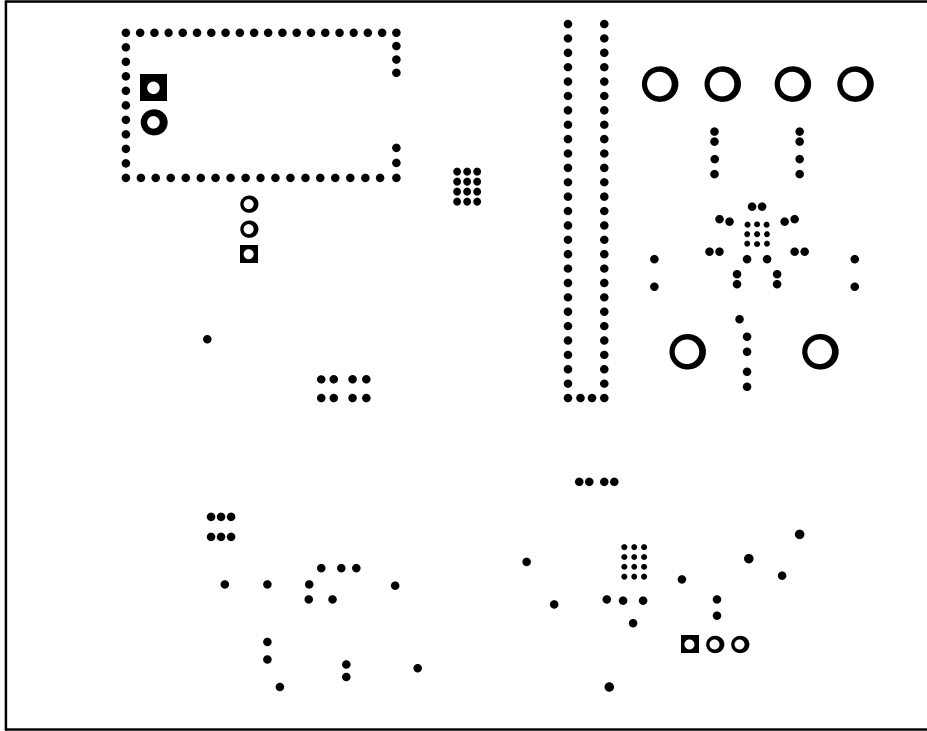
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LAYER NAME = M1 Board Outline			
PLOT NAME = Inner Layer 2	GENERATED : 9/3/2014 4:16:03 PM	TEXAS INSTRUMENTS	



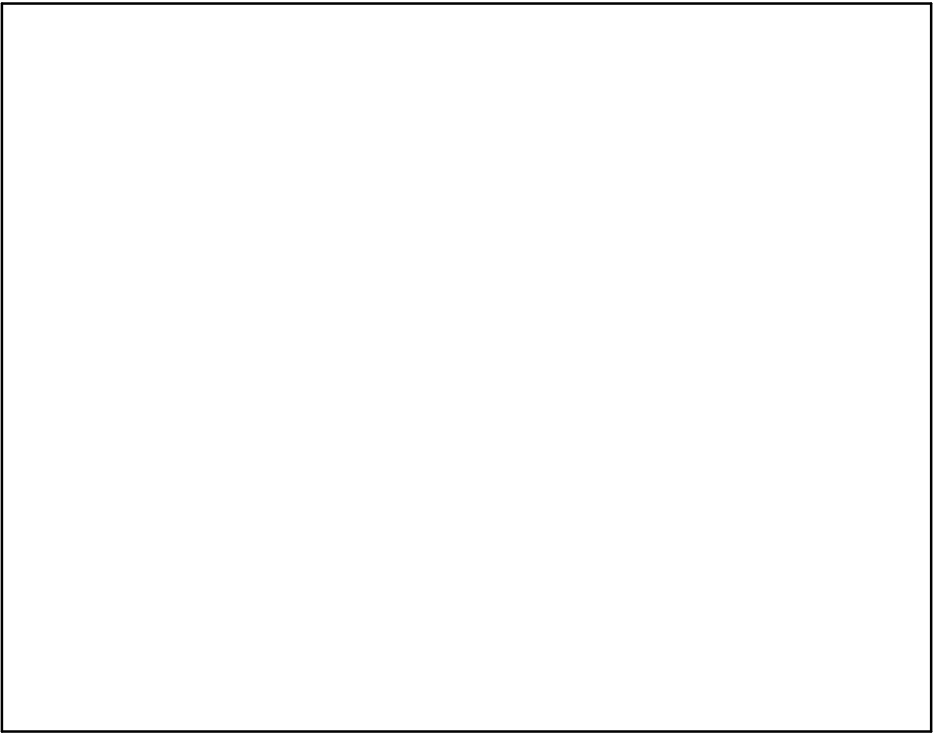
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9477	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Inner Layer 1	GENERATED : 9/3/2014 4:16:03 PM	TEXAS INSTRUMENTS	



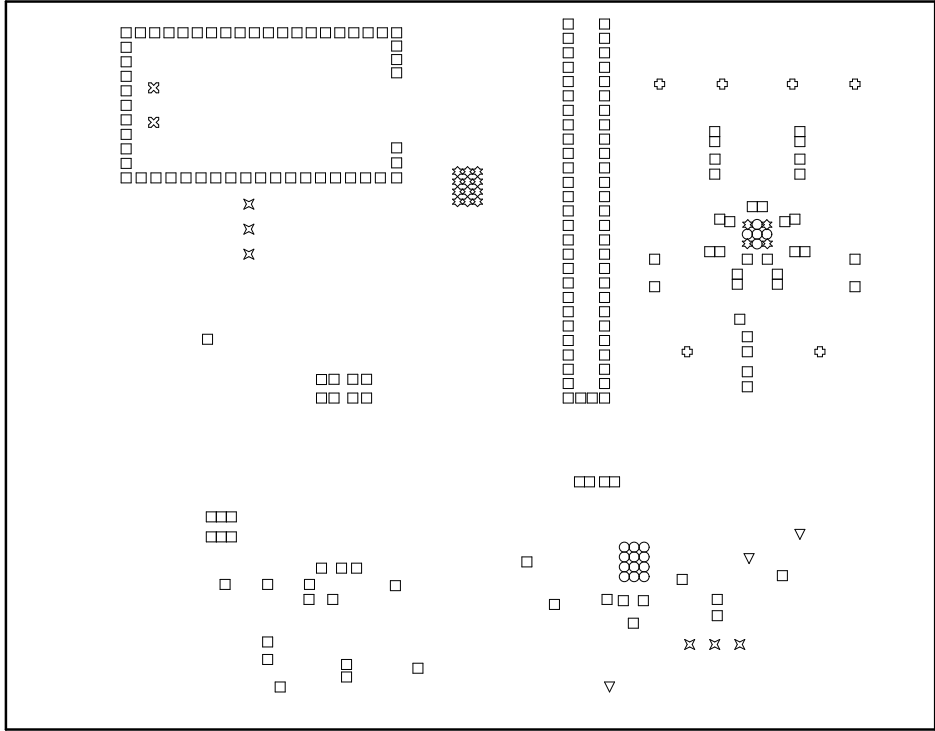
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9477	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 9/3/2014 4:16:04 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9477	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 9/3/2014 4:16:05 PM	TEXAS INSTRUMENTS	



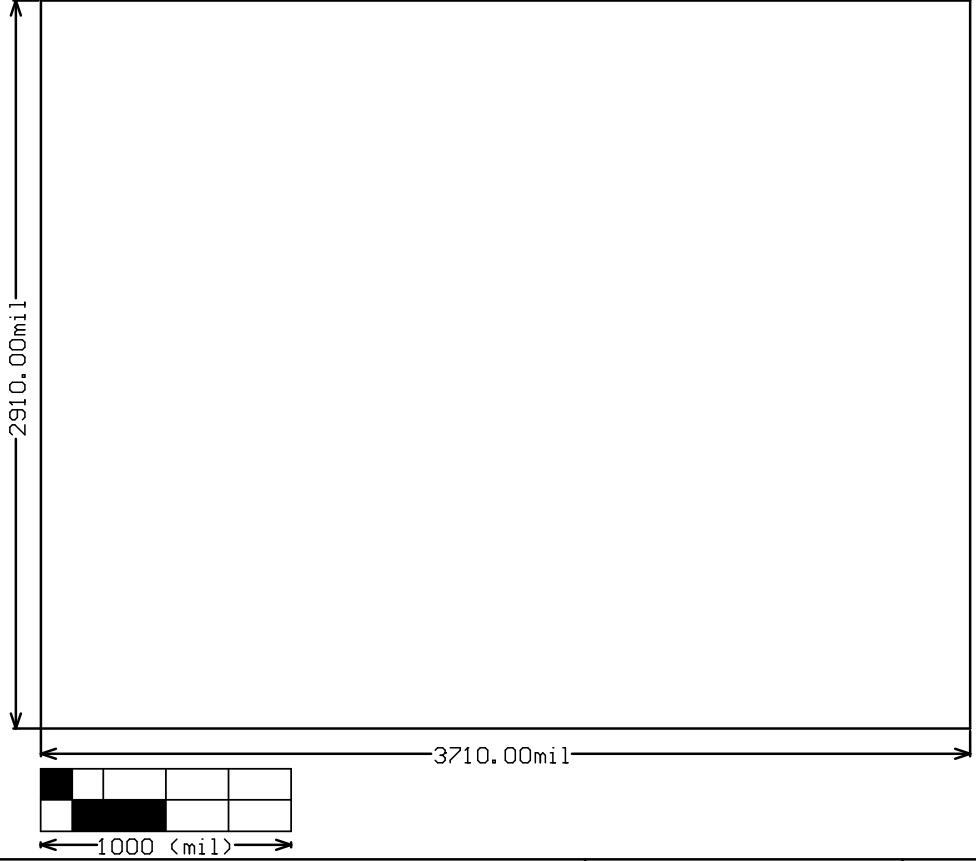
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9477	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 9/3/2014 4:16:05 PM	TEXAS INSTRUMENTS	



Symbol	Hit Count	Tool Size	Plated	Hole Type
○	17	7.874mil (0.2mm)	PTH	Round
☆	16	8mil (0.203mm)	PTH	Round
□	186	15mil (0.381mm)	PTH	Round
▽	3	16mil (0.406mm)	PTH	Round
✕	6	40mil (1.016mm)	PTH	Round
⊗	2	50mil (1.27mm)	PTH	Round
⊕	6	98.425mil (2.5mm)	PTH	Round
236 Total				

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9477	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 9/3/2014 4:16:06 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP9477	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 9/3/2014 4:16:06 PM	TEXAS INSTRUMENTS	

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